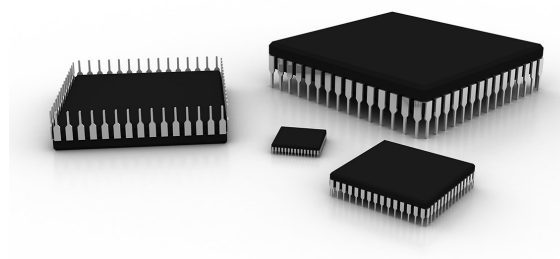


PALLUNA® 452 Palladium Electrolyte

Pure palladium electrolyte with excellent bonding and solderability

PALLUNA® 452 is a weakly ammoniacal electrolyte for the deposition of palladium in continuous systems and rack plating. It is used especially where excellent bondability and solderability are required.

The electrolyte has already been used for years in semiconductor technology and is mainly used in selective high-speed deposition. It is particularly suitable for systems with immersion cells, belt cells, brush cells, jet and spot systems.



Electrolyte characteristics

Electrolyte type	weakly ammoniacal
Metal content	3 (2.5 - 7) g/l Pd
pH value	8.0 (7.5 - 8.4)
Operating temperature	55 (50 - 60) °C
Current density range	1 - 2 A/dm ²
Plating speed	ca. 0.25 µm/min bei 1 A/dm ² ca. 0.50 µm/min bei 2 A/dm ²
Anode material	PLATINODE® 167

Coating characteristics

Coating	Pure palladium
Purity	99.9 wt.% Pd
Colour of deposit	white
Brightness	matt

Max. coating thickness

approx. 0.3 μm

Density of the coating

approx. 12 g/cm^3

Advantages

- Excellent bonding and solderability
- High deposition rate
- Simple electrolyte feed
- For continuous lines and rack plating

Applications

- Lead frames

Your contact person



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